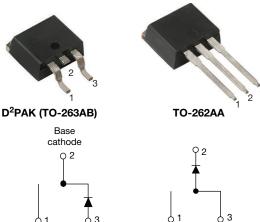
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VS-MURB1520-M3, VS-MURB1520-1-M3

Vishay Semiconductors

Ultrafast Rectifier, 15 A FRED Pt[®]



3 ሰ N/C Anode

VS-MURB1520-M3

VS-MURB1520-1-M3

Anode

N/C

PRIMARY CHARACTE	PRIMARY CHARACTERISTICS				
I _{F(AV)}	15 A				
V _R	200 V				
V _F at I _F	0.85 V				
t _{rr}	35 ns				
T _J max.	175 °C				
Package	D ² PAK (TO-263AB), TO-262AA				
Circuit configuration	Single				

FEATURES

- Ultrafast recovery time
- · Low forward voltage drop
- Low leakage current
- 175 °C operating junction temperature
- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

DESCRIPTION / APPLICATIONS

MUR.. series are the state of the art ultrafast recovery rectifiers specifically designed with optimized performance of forward voltage drop and ultrafast recovery time.

The planar structure and the platinum doped life time control, guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in the output rectification stage of SMPS, UPS, DC/DC converters as well as freewheeling diode in low voltage inverters and chopper motor drives.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Peak repetitive reverse voltage	V _{RRM}		200	V
Average rectified forward current	I _{F(AV)}	Total device, rated V _R , T _C = 150 °C	15	
Non-repetitive peak surge current	I _{FSM}		200	А
Peak repetitive forward current	I _{FM}	Rated V _R , square wave, 20 kHz, T _C = 150 °C	30	
Operating junction and storage temperatures	T _J , T _{Stg}		-65 to +175	°C

ELECTRICAL SPEC	IFICATIO	NS ($T_J = 25 \ ^{\circ}C$ unless otherwise specified	(b			
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	V _{BR} , V _R	I _R = 100 μA	200	-	-	N
Forward voltage	VF	I _F = 15 A	-	-	1.05	V
Forward voltage	۷F	I _F = 15 A, T _J = 150 °C	-	-	0.85	
Povoroo lookogo ourropt	1	$V_{R} = V_{R}$ rated	-	-	10	
Reverse leakage current	I _R	$T_J = 150 \text{ °C}, V_R = V_R \text{ rated}$	-	-	500	μA
Junction capacitance	CT	V _R = 200 V	-	55	-	pF
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8.0	-	nH

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DYNAMIC RECOVERY	CHARAC	TERISTICS (T_J :	= 25 °C unless otl	nerwise sp	ecified)		
PARAMETER	SYMBOL	TEST CO	NDITIONS	MIN.	TYP.	MAX.	UNITS
		$I_F = 1.0 \text{ A}, \text{ d}I_F/\text{d}t =$	50 A/µs, V _R = 30 V	-	-	35	
Reverse recovery time	t _{rr}	T _J = 25 °C		-	22	-	ns
		T _J = 125 °C		-	39	-	
Deak receivery ourrent	1	T _J = 25 °C	l _F = 15 A dl _F /dt = 200 A/µs	-	1.6	-	А
Peak recovery current	I _{RRM}	T _J = 125 °C	$V_{\rm R} = 160 \text{V}$	-	4.1	-	A
Reverse recovery charge	0	T _J = 25 °C	VR - 100 V	-	19	-	nC
neverse recovery charge	Q _{rr}	T _J = 125 °C		-	90	-	

THERMAL - MECHAN		CIFICATIONS				
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	T _J , T _{Stg}		-65	-	175	°C
Thermal resistance, junction-to-case	R _{thJC}		-	-	1.5	
Thermal resistance, junction-to-ambient	R _{thJA}		-	-	50	°C/W
Thermal resistance, case-to-heatsink	R _{thCS}	Mounting surface, flat, smooth, and greased	-	0.5	-	
Maight			-	2.0	-	g
Weight			-	0.07	-	oz.
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)
Marking davias		Case style D ² PAK (TO-263AB)		MUR	B1520	
Marking device		Case style TO-262		MURB	1520-1	

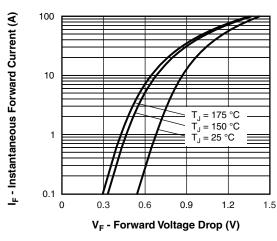


Fig. 1 - Typical Forward Voltage Drop Characteristics

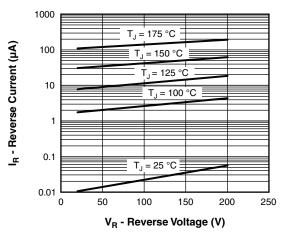


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage



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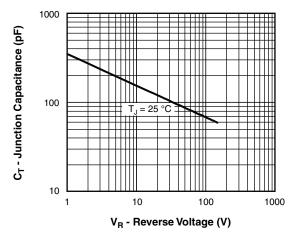


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

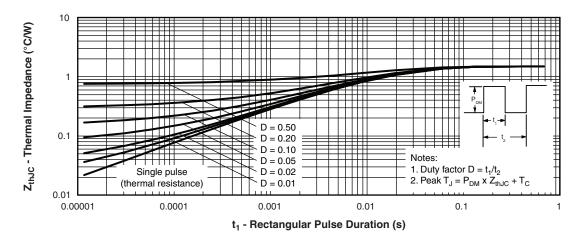
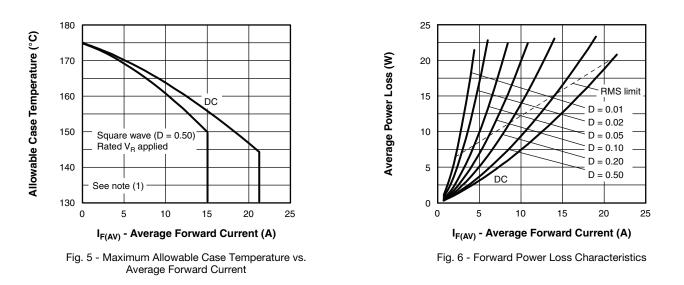


Fig. 4 - Maximum Thermal Impedance ZthJC Characteristics



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V_R = 160 V

T_J = 125 °C

= 30 A

= 15 A

= 8 A

<u>;</u> |>

T_j = 25 °C

200

160

120

80

40

0

100

Q_{rr} (nC)



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Z

1000

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dl_F/dt (A/µs)

Fig. 8 - Typical Stored Charge vs. dl_F/dt

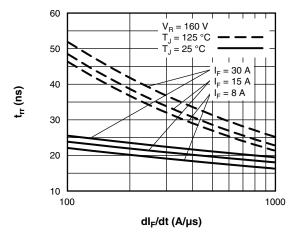


Fig. 7 - Typical Reverse Recovery Time vs. dl_F/dt



 $^{(1)} \mbox{ Formula used: } T_C = T_J - (Pd + Pd_{REV}) \ x \ R_{thJC}; \\ Pd = \mbox{ forward power loss = } I_{F(AV)} \ x \ V_{FM} \ at \ (I_{F(AV)}/D) \ (see \ fig. \ 6); \\ Pd_{REV} = \mbox{ inverse power loss = } V_{R1} \ x \ I_R \ (1 - D); \ I_R \ at \ V_{R1} = \ rated \ V_R$

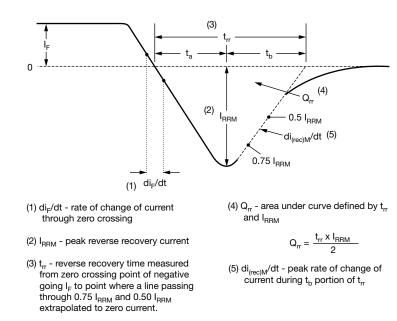
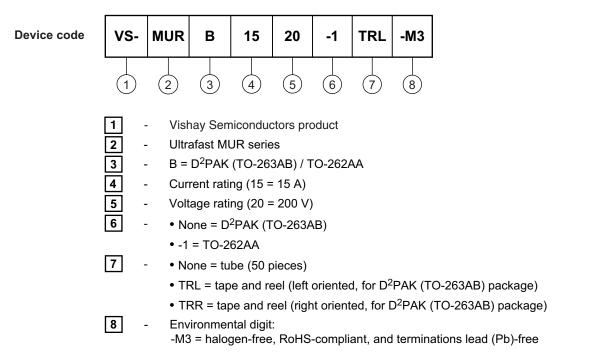


Fig. 9 - Reverse Recovery Waveform and Definitions



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ORDERING INFORMATION TABLE



ORDERING INFORMATION (Exar	nple)	
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION
VS-MURB1520-M3	50	Antistatic plastic tubes
VS-MURB1520TRR-M3	800	13" diameter plastic tape and reel
VS-MURB1520TRL-M3	800	13" diameter plastic tape and reel
VS-MURB1520-1-M3	50	Antistatic plastic tubes

LINKS TO RELATED DOCUMENTS					
Dimensions	D ² PAK (TO-263AB)	www.vishay.com/doc?96164			
Dimensions	TO-262AA	www.vishay.com/doc?96165			
Part marking information	D ² PAK (TO-263AB)	www.vishay.com/doc?95444			
Fart marking information	TO-262AA	www.vishay.com/doc?95443			
Packaging information		www.vishay.com/doc?96424			
SPICE model		www.vishay.com/doc?95271			

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D²PAK

DIMENSIONS in millimeters and inches



ota	ted	90	°C
<u>S</u>	cale	<u>ə:</u> 8	:1

SYMBOL	MILLIM	ETERS	INC	HES	NOTES	
STMBOL	MIN.	MAX.	MIN.	MAX.	NOTES	
А	4.06	4.83	0.160	0.190		
A1	0.00	0.254	0.000	0.010		
b	0.51	0.99	0.020	0.039		
b1	0.51	0.89	0.020	0.035	4	
b2	1.14	1.78	0.045	0.070		
b3	1.14	1.73	0.045	0.068	4	
с	0.38	0.74	0.015	0.029		
c1	0.38	0.58	0.015	0.023	4	
c2	1.14	1.65	0.045	0.065		
D	8.51	9.65	0.335	0.380	2	

SYMBOL	MILLIM	ETERS	INC	HES	NOTES
STNDUL	MIN.	MAX.	MIN.	MAX.	NOTES
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
е	2.54 BSC		0.100 BSC		
Н	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	-	1.65	-	0.066	3
L2	1.27	1.78	0.050	0.070	
L3	0.25	BSC	0.010	BSC	
L4	4.78	5.28	0.188	0.208	

Notes

⁽¹⁾ Dimensioning and tolerancing per ASME Y14.5 M-1994

(2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body

(3) Thermal pad contour optional within dimension E, L1, D1 and E1

⁽⁴⁾ Dimension b1 and c1 apply to base metal only

(5) Datum A and B to be determined at datum plane H

(6) Controlling dimension: inches

⁽⁷⁾ Outline conforms to JEDEC[®] outline TO-263AB

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Outline Dimensions



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TO-262AA

DIMENSIONS in millimeters and inches





F D1 (3) (3) Section A - A Base (4) Plating b1. b3 metal ≰ c1 (4) -(b, b2)-Section B - B and C - C Scale: None





Diodes 1. - Anode (two die)/open (one die) 2., 4. - Cathode 3. - Anode

Lead assignments

SYMBOL	MILLIN	IETERS	INC	HES	NOTES
	MIN.	MAX.	MIN.	MAX.	NOTES
А	4.06	4.83	0.160	0.190	
A1	2.03	3.02	0.080	0.119	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
С	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
е	2.54	BSC	0.100) BSC	
L	13.46	14.10	0.530	0.555	
L1	-	1.65	-	0.065	3
L2	3.56	3.71	0.140	0.146	

 ⁽¹⁾ Dimensioning and tolerancing as per ASME Y14.5M-1994
⁽²⁾ Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the second dimensioner of the second dimensis and the second dimensioner of the second dimensioner of the the outmost extremes of the plastic body (3)

Thermal pad contour optional within dimension E, L1, D1 and E1

⁽⁴⁾ Dimension b1 and c1 apply to base metal only (5)

Controlling dimension: inches

(6) Outline conform to JEDEC® TO-262 except A1 (max.), b (min., max.), b1 (min.), b2 (max.), c (min.), c1(min.), c2 (max.), D (min.), E (max.), L1 (max.), L2 (min., max.)

Revision: 30-Nov-17

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